

Application No.: 10/803,787

2

Docket No.: 524322001100

**Amendments to the Specification:**

Please replace paragraph [0004] with the following amended paragraph:

[0004] During mass manufacture of ICs, defects may exist in some of the ICs produced. For example, variations can be introduced during the fabrication process that adversely affects specific locations on a wafer. If these variations are too far from specified tolerances, an IC may not function properly when tested. Some ICs may be ~~reparable~~ repairable while others may not be. If after testing and repair these ICs are unusable, the ICs may be labeled defective and discarded.

Please replace paragraph [0019] with the following amended paragraph:

[0019] In one exemplary embodiment, tester 106 performs one or more tests on a particular IC or portion of an IC formed on each one of the wafers 102. In the present exemplary embodiment, processor 108 obtains the actual yield value associated with the particular IC or portion of an IC. In ~~particularly-particular~~, processor 108 can determine the number of particular ICs or portions of an IC that passed the one or more tests. Processor 108 can then calculate the actual yield value as a ratio of the number of particular ICs or portions of an IC that passed the one or more tests and a total number of particular ICs or portions of an IC tested.

sf-1958094